# fineon

# 2006 Financial Year Roadshow

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# Disclaimer

Please note that while you are reviewing this information, this presentation was created as of the date listed, and reflected management views as of that date.

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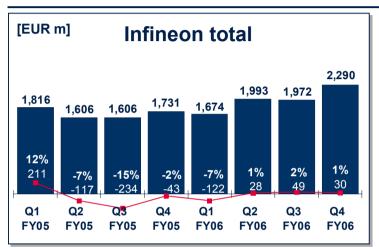
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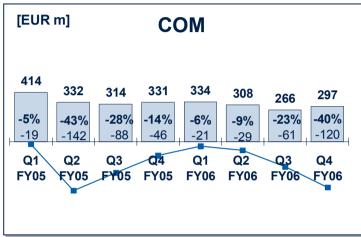


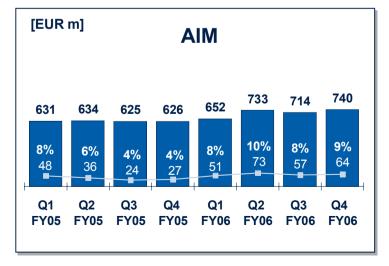
- Infineon: Competencies & Drivers
- **Communication Solutions**
- Automotive, Industrial & Multimarket
  - Appendix (Key Financials, Ratios, Financial Calendar)

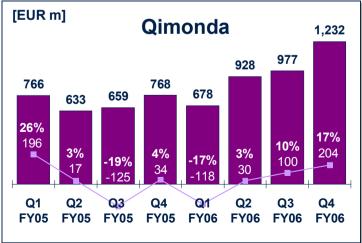


# Q4 FY 06 Results: Revenues of EUR 2.29 bn and EBIT of EUR 30 m





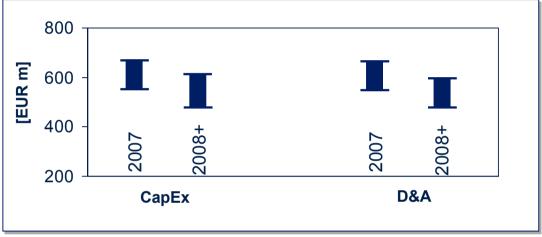




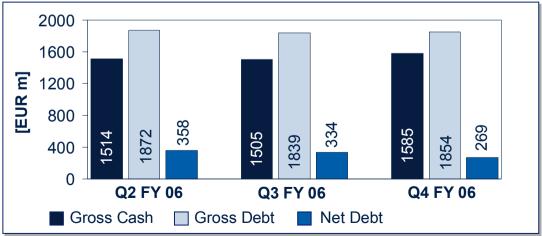


# Capital Intensity and Financing of IFX Logic

Outlook for CapEx and D&A



Financial structure
Logic-business for the past quarters



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# Business Groups' Q1 FY07 Outlook

Revenues and EBIT, excluding Qimonda and before charges, to decrease, driven mainly by the impact of the insolvency of BenQ Mobile's German subsidiary on COM.



COM revenues and EBIT are expected to decline significantly qoq, mainly due to loss of business as a result of the insolvency of the German subsidiary of BenQ Mobile.



- Revenues flat or down slightly from high Q4 level; EBIT to decrease qoq driven by seasonality and temporary effects.
- Revenues and EBIT in auto to decrease slightly qoq given seasonality and volume reductions at U.S. car manufacturers.
- Industrial revenue to grow slightly; EBIT to decline given lack of scale economies in Kulim fab.
- ASIC and chipcard seasonally weak.



- Anticipated EBIT improvement before restructuring charges qoq.
- Potential charges of approximately Euro 30 million expected, resulting from planned restructuring in baseband.



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# Key Growth Drivers / Focus Areas

### **Energy Efficiency (fuel / electricity)**

- Improve fuel efficiency in cars
- Efficient power generation, transport, consumption
- Higher efficiency in electrical drives



# **Mobility & Connectivity**

- Mobile phones
- Broadband access
- Wireless connectivity



# **Security & Safety**

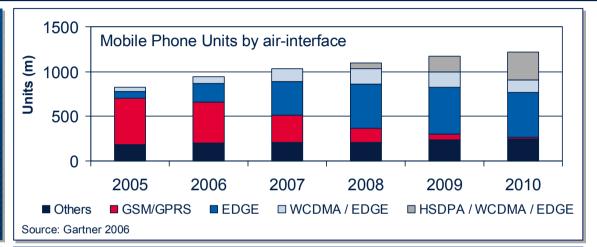
- Protection and privacy of personal and company data
- Secure e-commerce and identification
- Automotive safety



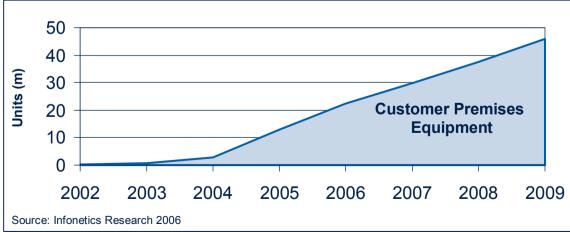


# **COM Growth Drivers**





# Connectivity



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# **AIM Growth Drivers**

# **Energy Efficiency**

### **Different governmental requirements:**

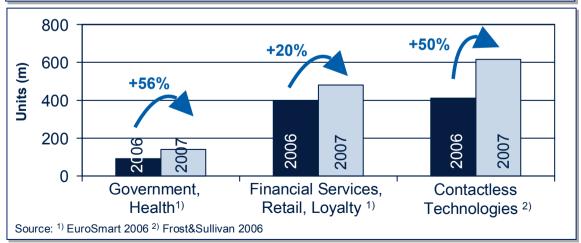
Europe: Euro 5 norm coming 2009

**USA:** Energy Star, July 2007, will require PC's to be 65% more power efficient than current models.

Japan: already highest regulatory standards



# Security & Safety





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# Broadband Access Design-Win Momentum Continues

<b>VDS</b>	L2
"VIN	IAX"

Design-Win at major Korean customers

■ Top European customer



ADSL2+ "Geminax-MAX"

Design-Win at two customers based in APAC

Major European customer



ADSL & VoIP "Amazon, Danube"

4 Design-Wins for ADSL & VolP

 2 of the top 5 world wide ADSL-CPE Manufacturer



VoIP "Vinetic"

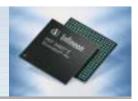
Design-Wins at two Japanese customers

Major global customer



SHDSL.bis "Socrates-4e" Leading Chinese DSLAM customer

Major global customer, based in EU





# RF Transceiver: CMOS Leadership Turns Into Design-Wins

### 2 / 2.5 G **GSM / GPRS**

2.75 G **EDGE** 

3 G **WCDMA** 

**SMARTI SD SMARTI SD2** 

**SMARTI PM SMARTI PM2** 

**SMARTI 3G SMARTI 3GE** 

Technology: 130nm CMOS

130nm CMOS

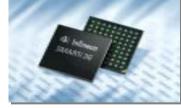
130nm CMOS

Customer	Air Interface				
Samsung	EDGE				
Customer	EDGE				
Customer	WCDMA				
Customer	WCDMA / EDGE				
LG (on platform)	EDGE				
Panasonic (on platform)	WCDMA / EDGE				

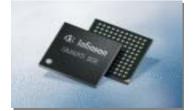












World's first WCDMA CMOS RF-Transceiver in volume





# RF/Baseband Integration, HSDPA and More

				75G DGE	3G UMTS	3.5G HSDPA
Platform	ULC1	ULC2		MP-E	MP-EU	MP-EH
Baseband	E-GOL Dradio	oice	dio	S-GOLD2	S-GOLD2 + co-processor	S-GOLD3H
RF Transceiver	E-GOL	-GOLDvoice (incl. SRAM)	OLDra	SMARTI PM	SMARTI PM/3G	SMARTI 3GE
Power Management	E-Powerlite	<b>E-G</b>	S-G	SM-Power	SM-Power1.6	SM-Power3
Protocol Stack	<b>✓</b>	✓		✓	✓	✓
Ramp up	✓	1H CY07		✓	✓	CY 2007+

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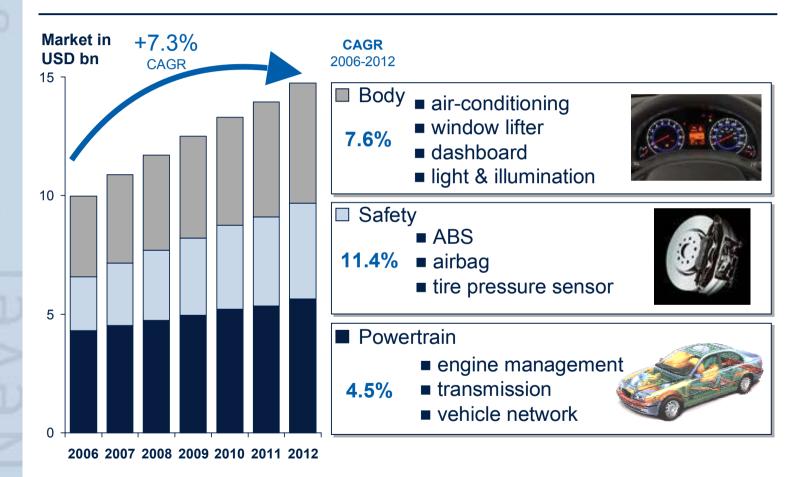
integrated in one chip



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# Worldwide Automotive Semiconductor Market Continues to Grow; Safety is the Fastest Growing Segment

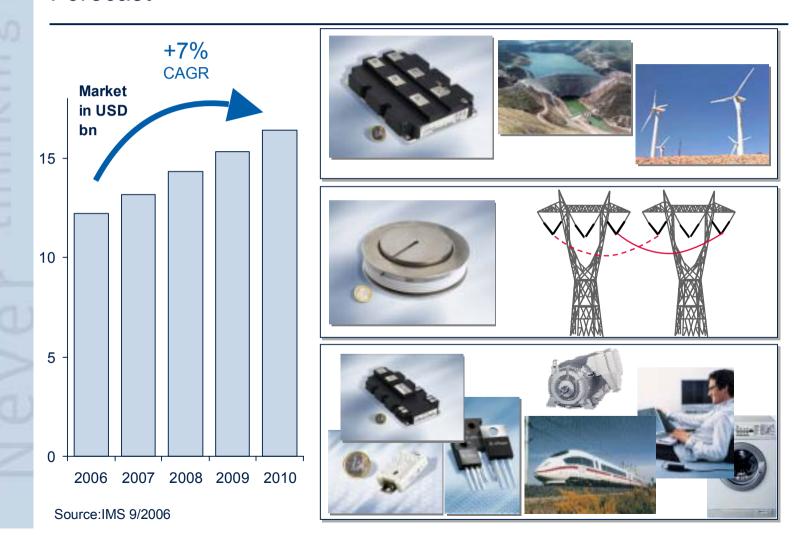


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Source: Strategy Analytics 9/2005



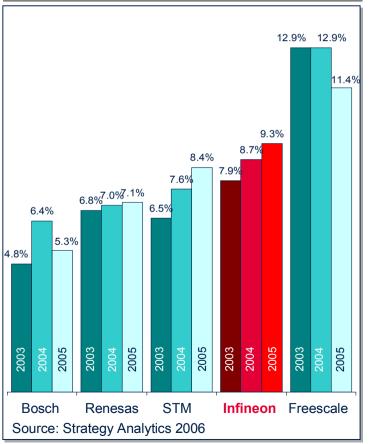
# Worldwide Power Semiconductor Market Growth Forecast





# Infineon's Track Record in Automotive and Power Semiconductor Market Shares

# Worldwide Automotive Semiconductor



### Worldwide Power Semiconductor

